

## AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application.

### Listing of Claims:

Claim 1 (Currently Amended): An implantable medical device comprising:

at least two interconnected modules, each of the modules comprising a respective one of  
at least two housings; and

an overmold that at least partially encapsulates each of the housings, the overmold  
comprising a lead connection module ~~for accepting~~ configured to accept an external lead.

Claim 2 (Original): The implantable medical device of claim 1, wherein at least one module comprises a control module containing electronic components.

**Claim 3 (Original):** The implantable medical device of claim 1, wherein the overmold comprises a first material and a second material, and the lead connection module is deployed within the first material.

**Claim 4 (Original):** The implantable medical device of claim 3, wherein the first material comprises a non-elastomeric material.

Claim 5 (Original): The implantable medical device of claim 1, the lead connection module comprising at least one feed-through wire to electrically couple an external lead to an electronic component within the implantable medical device.

**Claim 6 (Original):** The implantable medical device of claim 1, wherein the lead connection module includes a mechanical lead securing mechanism.

Claim 7 (Original): The implantable medical device of claim 6, wherein the mechanical lead securing mechanism comprises a tool-less mechanical lead securing mechanism.

Claim 8 (Original): The implantable medical device of claim 1, wherein the implantable medical device has a maximum thickness of between approximately 4 millimeters and approximately 8 millimeters.

Claim 9 (Currently Amended): An overmold for a modular implantable medical device that includes a plurality of modules, each of the modules comprising a respective housing, the overmold comprising:

- a first material configured to hold at least part of the housing of one of the a modules;
- a second material coupled to the first material; and
- a lead connection module configured to accept an external lead, the lead connection module being deployed within the overmold.

Claim 10 (Original): The overmold of claim 9, wherein the first material comprises a non-elastomeric material.

Claim 11 (Original): The overmold of claim 9, wherein the second material comprises an elastomeric material.

Claim 12 (Original): The overmold of claim 9, wherein the second material comprises silicone.

Claim 13 (Original): The overmold of claim 9, wherein the lead connection module is deployed within the first material.

Claim 14 (Original): The overmold of claim 9, wherein the lead connection module is configured to receive an iso-diametric external lead.